Freescale Semiconductor
Data Sheet: Technical Data

MPX5010
Rev 13, 10/2012

Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

MPX5010
MPXV5010
MPVZ5010
Series

0 to 10 kPa (0 to 1.45 psi)
(0 to 1019.78 mm H_2O)
0.2 to 4.7 V Output

The MPxx5010 series piezoresistive transducers are state-of-the-art monolithic silicon pressure sensors designed for a wide range of applications, but particularly those employing a microcontroller or microprocessor with A/D inputs. This transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high level analog output signal that is proportional to the applied pressure. The axial port has been modified to accommodate industrial grade tubing.

Features

- 5.0% Maximum Error over 0° to 85°C
- Ideally Suited for Microprocessor or Microcontroller-Based Systems
- Durable Epoxy Unibody and Thermoplastic (PPS) Surface Mount Package
- Temperature Compensated over -40° to +125°C
- Patented Silicon Shear Stress Strain Gauge
- Available in Differential and Gauge Configurations
- Available in Surface Mount (SMT) or Through-hole (DIP) Configurations

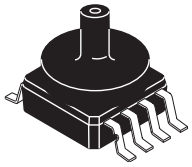
Application Examples

- Hospital Beds
- HVAC
- Respiratory Systems
- Process Control
- Washing Machine Water Level Measurement (Reference AN1950)
- Ideally Suited for Microprocessor or Microcontroller-Based Systems
- Appliance Liquid Level and Pressure Measurement

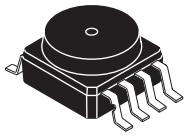
ORDERING INFORMATION

Device Name	Case No.	# of Ports			Pressure Type			Device Marking
		None	Single	Dual	Gauge	Differential	Absolute	
Unibody Package (MPX5010 Series)								
MPX5010DP	867C			•		•		MPX5010DP
MPX5010GP	867B		•		•			MPX5010GP
MPX5010GS	867E		•		•			MPX5010D
MPX5010GSX	867F		•		•			MPX5010D
Small Outline Package (MPXV5010 Series)								
MPXV5010DP	1351			•		•		MPXV5010DP
MPXV5010G6U	482	•			•			MPXV5010G
MPXV5010GC6T1	482A		•		•			MPXV5010G
MPXV5010GC6U	482A		•		•			MPXV5010G
MPXV5010GC7U	482C		•		•			MPXV5010G
MPXV5010GP	1369		•		•			MPXV5010GP
Small Outline Package (Media Resistant Gel) (MPVZ5010 Series)								
MPVZ5010G6U	482	•			•			MPVZ5010G
MPVZ5010G7U	482B	•			•			MPVZ5010G
MPVZ5010GW6U	1735		•		•			MZ5010GW
MPVZ5010GW7U	1560		•		•			MZ5010GW

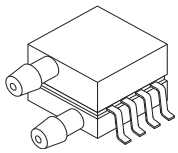
SMALL OUTLINE PACKAGES SURFACE MOUNT



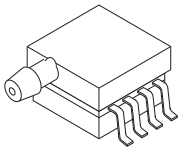
MPXV5010GC6U/C6T1
CASE 482A-01



MPXV5010G6U,
MPVZ5010G6U
CASE 482-01



MPXV5010DP
CASE 1351-01



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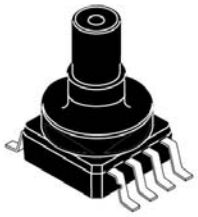
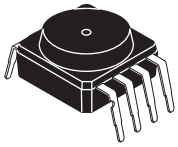
CASE 1369-01



MPVZ5010GW6U
CASE 1735-01

SMALL OUTLINE PACKAGES THROUGH-HOLE



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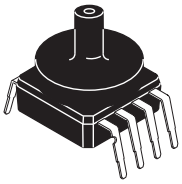
CASE 482B-03



MPXV5010GC7U
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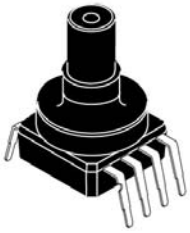
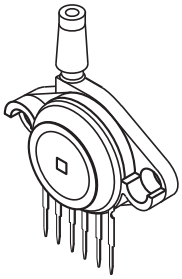


MPVZ5010GW7U
CASE 1560-02

UNIBODY PACKAGES



MPX5010GP
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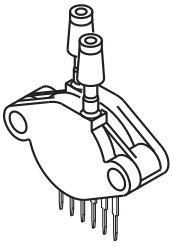

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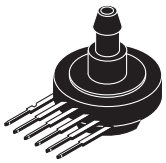
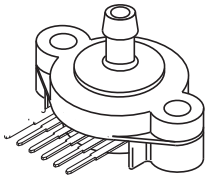


MPX5010GS
CASE 867E-03



MPX5010GSX
CASE 867F-03

Operating Characteristics

Table 1. Operating Characteristics (V_S = 5.0 Vdc, T_A = 25°C unless otherwise noted, P1 > P2. Decoupling circuit shown in Figure 3 required to meet specification.)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range		P_{OP}	0	—	10 1019.78	kPa mm H_2O
Supply Voltage(1)		V_S	4.75	5.0	5.25	Vdc
Supply Current		I_o	—	5.0	10	mAdc
Minimum Pressure Offset(2) @ V_S = 5.0 Volts	(0 to 85°C)	V_{off}	0	0.2	0.425	Vdc
Full Scale Output(3) @ V_S = 5.0 Volts	(0 to 85°C)	V_{FSO}	4.475	4.7	4.925	Vdc
Full Scale Span(4) @ V_S = 5.0 Volts	(0 to 85°C)	V_{FSS}	4.275	4.5	4.725	Vdc
Accuracy(5)	(0 to 85°C)	—	—	—	±5.0	$\%V_{FSS}$
Sensitivity		V/P	—	450 4.413	—	mV/mm mV/mm H_2O
Response Time(6)		t_R	—	1.0	—	ms
Output Source Current at Full Scale Output		I_{O+}	—	0.1	—	mAdc
Warm-Up Time(7)		—	—	20	—	ms
Offset Stability(8)		—	—	±0.5	—	$\%V_{FSS}$

1. Device is ratiometric within this specified excitation range.
2. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
3. Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
4. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
5. Accuracy (error budget) consists of the following:

   Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.

   Temperature Hysteresis:Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.

   Pressure Hysteresis:Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.

   TcSpan: Output deviation over the temperature range of 0° to 85°C, relative to 25°C.

   TcOffset:Output deviation with minimum rated pressure applied, over the temperature range of 0° to 85°C, relative to 25°C.

   Variation from Nominal:The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS}, at 25°C.
6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
8. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

Maximum Ratings

Table 2. Maximum Ratings(1)

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P_{max}	40	kPa
Storage Temperature	T_{stg}	–40 to +125	°C
Operating Temperature	T_A	–40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

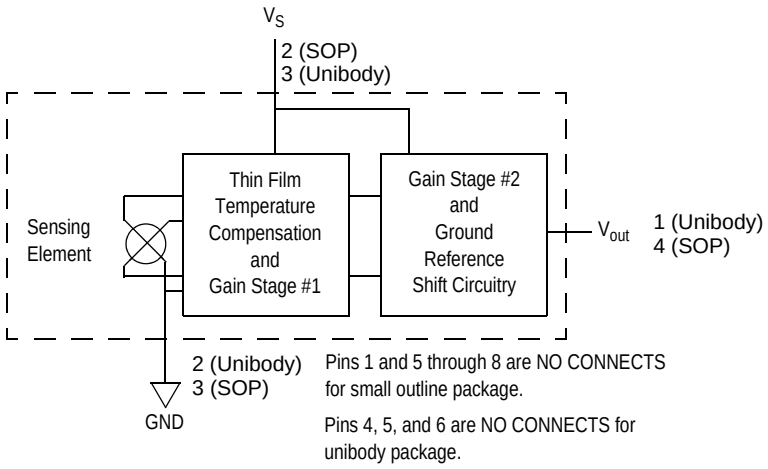


Figure 1. Fully Integrated Pressure Sensor Schematic

ON-CHIP TEMPERATURE COMPENSATION AND CALIBRATION

The performance over temperature is achieved by integrating the shear-stress strain gauge, temperature compensation, calibration and signal conditioning circuitry onto a single monolithic chip.

Figure 3 illustrates the Differential or Gauge configuration in the basic chip carrier (Case 482). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MPxx5010G series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 4 shows the recommended decoupling circuit for interfacing the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

Figure 5 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 4. The output will saturate outside of the specified pressure range.

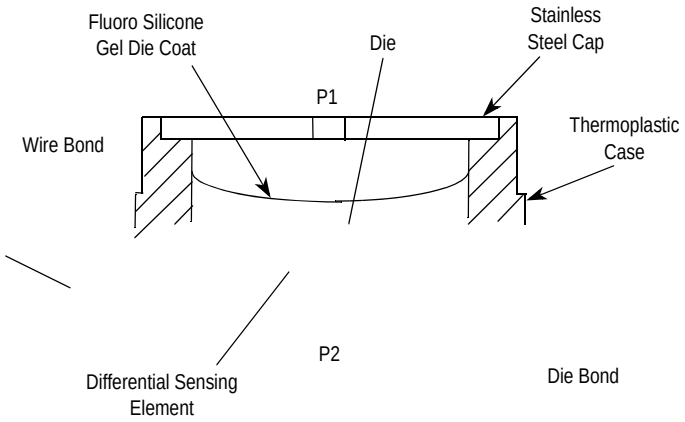


Figure 2. Cross-Sectional Diagram SOP (not to scale)

Figure 3. Recommended Power Supply Decoupling and Output Filtering
(For additional output filtering, please refer to Application Note AN1646.)

Figure 4. Output vs. Pressure Differential

PACKAGE DIMENSIONS

NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PPROTRUSIONS.
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.

4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
PROTRUSION SHALL BE .008 MAXIMUM.

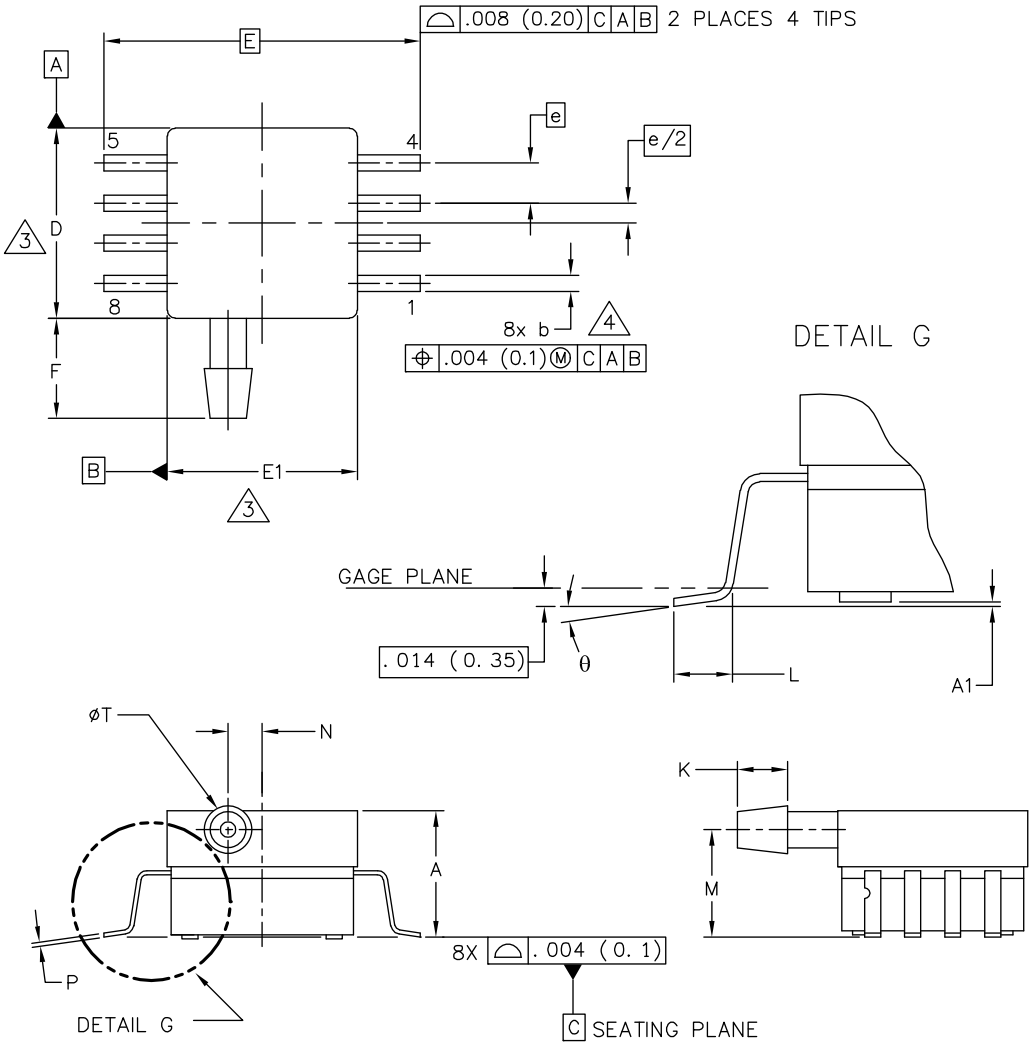
STYLE 1:	STYLE 2:
PIN 1: GND	PIN 1: N/C
PIN 2: +Vout	PIN 2: Vs
PIN 3: Vs	PIN 3: GND
PIN 4: –Vout	PIN 4: Vout
PIN 5: N/C	PIN 5: N/C
PIN 6: N/C	PIN 6: N/C
PIN 7: N/C	PIN 7: N/C
PIN 8: N/C	PIN 8: N/C

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ASA99255D	REV: A
8 LD SNSR, DUAL PORT	CASE NUMBER: 1351–01	27 JUL 2005
	STANDARD: NON–JEDEC	

CASE 1351-01
ISSUE A
SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 8 LD SOP, SIDE PORT	DOCUMENT NO: 98ASA99303D	REV: B
	CASE NUMBER: 1369-01	24 MAY 2005
	STANDARD: NON-JEDEC	

CASE 1369-01
ISSUE B
SMALL OUTLINE PACKAGE

PACKAGE DIMENSIONS

NOTES:
1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PPROTRUSIONS.
   MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 (0.152) PER SIDE.

4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
   PROTRUSION SHALL BE .008 (0.203) MAXIMUM.

DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX	DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.300	.330	7.11	7.62					
A1	.002	.010	0.05	0.25					
b	.038	.042	0.96	1.07					
D	.465	.485	11.81	12.32					
E	.717 BSC		18.21 BSC						
E1	.465	.485	11.81	12.32	–	---	---	---	---
e	.100 BSC		2.54 BSC		–	---	---	---	---
F	.245	.255	6.22	6.47	–	---	---	---	---
K	.120	.130			–	---	---	---	---
L	.061	.071	1.55	1.80	–	---	---	---	---
M	.270	.29˚			–	---	---	---	---
P	.009	.011	0.23	0.28	–	---	---	---	---
T	.115	.125	2.92	3.17	–	---	---	---	---

CASE 1369-01
ISSUE B
SMALL OUTLINE PACKAGE